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Term: 110 and (acid or acidic or ph) with (silica or silicon or "sio.sub.2" or sio2 or abrasive) and (basic or alkali or ph) near substance

Display: 10 Documents in Display Format: - Starting with Number 1

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Search History

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side by side		result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L14</u> 110 and (acid or acidic or ph) with (silica or silicon or "sio.sub.2" or sio2 or abrasive) and (basic or alkali or ph) near substance	7	<u>L14</u>
<u>L13</u> 112 not 111	17	<u>L13</u>
<u>L12</u> 110 and (acid or acidic or ph) with (silica or silicon or "sio.sub.2" or sio2 or abrasive) and (basic or alkali or ph) near solution	59	<u>L12</u>
<u>L11</u> 110 and (acid or acidic or ph) near4 (silica or silicon or "sio.sub.2" or sio2 or abrasive) and (basic or alkali or ph) near solution	42	<u>L11</u>
<u>L10</u> bulk density and (fumed or fume) (silica or silicon or "sio.sub.2" or sio2) and (polishing or planarizing or planarization or abrasive or cmp or polish)	264	<u>L10</u>
<u>L9</u> L8 and bulk density	2	<u>L9</u>
<u>L8</u> L7 and (fumed or fume) (silica or silicon or "sio.sub.2" or sio2)	95	<u>L8</u>
<u>L7</u> (acid or acidic or ph) near4 silica and (polishing or planarizing or planarization or abrasive or cmp or polish).ti. and (basic or alkali or ph) near solution	247	<u>L7</u>
<i>DB=PGPB,USPT; PLUR=YES; OP=ADJ</i>		
<u>L6</u> 13 and 15	0	<u>L6</u>

5116535.pn. or 5246624.pn. or 6248144.pn. or 6409780.pn. 4 L5
L4 20020028636 or 20040040217 or 5116535.pn. or 5246624.pn. or 6248144.pn. 7 L4
L3 (acid or acidic) near4 silica and (polishing or planarizing or planarization or 32 L3
abrasive or cmp or polish).ti. and (basic or alkali) solution
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ
L2 L1 and (acid or acidic) fumed silica 1 L2
(polishing or planarizing or planarization or abrasive or cmp or polish).ti. and
(abrasive or silica or silicon dioxide or silicon oxide or (polishing or planarizing
L1 or planarization or cmp) (particle or particulate or grit or grain)) with (volume 68 L1
or vol or "vol." or "vol.%" of "vol%") with (size or diameter) with (nm or
nanometer)

END OF SEARCH HISTORY